

## AMENDMENT

In response to the Final Office Action of March 13, 2003 please amend the above-identified application as follows:

**In the Claims:**

Please amend claim 1 as follows:

1. (TWICE AMENDED) A polishing-dressing head for a polishing apparatus comprising:

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a plurality of substrate head assemblies each having a lower nesting surface opposed to an upper surface of a polishing pad, said lower nesting surface releasably holds a substrate to be polished, said substrate head assemblies, each rotating along a central axis thereof and polishing the substrates on an outer radial portion of said rotating polishing pad;  
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annular dressing rings for dressing said polishing pad, said dressing rings are positioned coaxially encircling each nested substrate, said annular dressing rings are removably attached to said lower surface of said substrate head assemblies, and  
means for simultaneously applying a polishing and dressing pressure to said head assemblies, whereby the substrate head assemblies are urged against the upper surface of the rotating polishing pad.

2. (AMENDED) The apparatus according to claim 1 wherein coaxially combining said annular dressing rings with said plurality of substrate head assemblies, simultaneously polishes all of said substrates while dressing said

polishing pad.

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a 3. (AMENDED) The apparatus according to claim 1 wherein said polishing pad is treated with a suitable polishing slurry for polishing said substrates.

C2 5. (AMENDED) The apparatus according to claim 4 wherein said dressing ring material that makes contacts with said polishing pad is ceramic.

6. (AMENDED) The apparatus according to claim 5 wherein said ceramic portion making contact with said polishing pad includes a glass frit binder.

C3 7. (AMENDED) The apparatus according to claim 6 wherein said ceramic portion making contact with said polishing pad has inclusions of sintered diamond abrasive.

8. (AMENDED) The apparatus according to claim 1 wherein coaxially combining said dressing ring with said substrate head assembly eliminates the need of a separate dressing station.

45 9. (AMENDED) The apparatus according to claim 8 wherein eliminating the need of a separate dressing station increases machine throughput.

50 10. (AMENDED) The apparatus according to claim 1 wherein coaxially combining said dressing ring with said substrate head assembly on a chemical mechanical polishing machine improves polishing uniformity and process stability.

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11. (AMENDED) The apparatus according to claim 1 wherein coaxially combining said dressing ring with said substrate head assembly simplifies the structure of the machine while improving maintainability.

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